

## 2.0X1.2X0.6 (mm) WiFi/Bluetooth Ceramic Chip Antenna (YF2012-1) Engineering Specification

### 1. Product Number

YF      2012      H2      P      2G45  
1          2          3          4          5

|                  |              |
|------------------|--------------|
| (1)Product Type  | Chip Antenna |
| (2)Size Code     | 2.0x1.2mm    |
| (3)Type Code     | H2           |
| (4)Packing       | Paper &Reel  |
| (5)Frequency     | 2.45GHz      |
| (6)Internal code | 00           |



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Prepared by : JIEXI

Designed by : Jason

Checked by : Jason

Approved by : MR.FANG

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## 2. Features

- \*Stable and reliable in performances
- \*Low temperature coefficient of frequency
- \*Low profile, compact size
- \*RoHS compliance
- \*SMT processes compatible

## 3. Applications

- \*Bluetooth earphone systems
- \*Hand-held devices when WiFi /Bluetooth functions are needed, e.g., Smart phone.
- \*IEEE802.11 b/g/n
- \*ZigBee
- \*Wireless PCMCIA cards or USB dongle

## 4. Description

Yingfeng chip antenna series are specially designed for WiFi/Bluetooth applications. Based on yingfeng proprietary design and processes, this chip antenna has excellent stability and sensitivity to consistently provide high signal reception efficiency.

## 5. Electrical Specifications (80 x 40 mm<sup>2</sup> ground plane)

5-1. Electrical Table

| Characteristics    |            | Specifications      | Unit |
|--------------------|------------|---------------------|------|
| Outline Dimensions |            | 2.0x1.2x0.6         | mm   |
| Working Frequency  |            | 2400~2500           | MHz  |
| VSWR               |            | 2 Max.              |      |
| Impedance          |            | 50                  | Ω    |
| Polarization       |            | Linear Polarization |      |
| Gain               | Peak       | 2.5 (typical)       | dBi  |
|                    | Efficiency | 75 (typical)        | %    |



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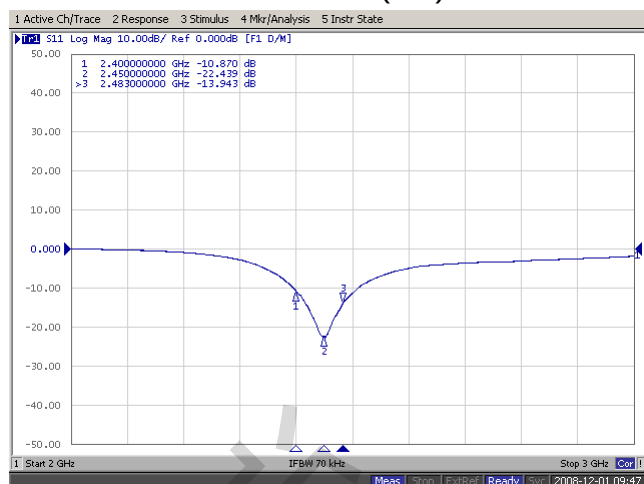
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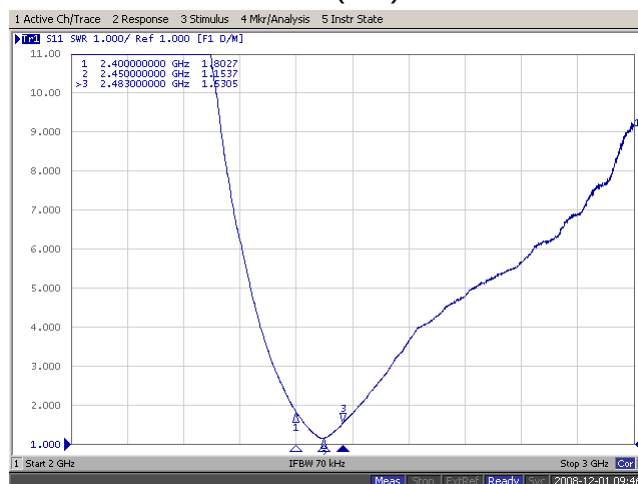
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## 5-2. Return Loss & VSWR

Return Loss (S<sub>11</sub>)

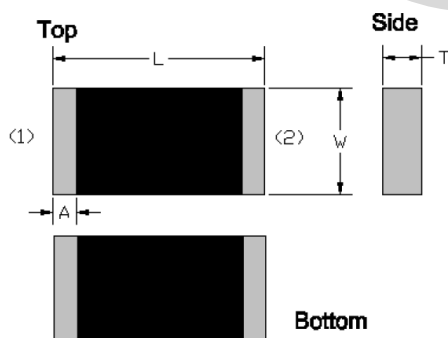


VSWR(S<sub>11</sub>)



## 6. Antenna Dimensions & Test Board (unit: mm)

### a. Antenna Dimensions



| Dimension (mm) |           |
|----------------|-----------|
| L              | 2.05+0.15 |
| W              | 1.20+0.15 |
| T              | 0.50+0.10 |
| A              | 0.20+0.10 |

| No. | Terminal Name |
|-----|---------------|
| 1   | Feeding/GNG   |
| 2   | GND/Feeding   |

P.S : Top & down and left & right side are symmetrical, No direction



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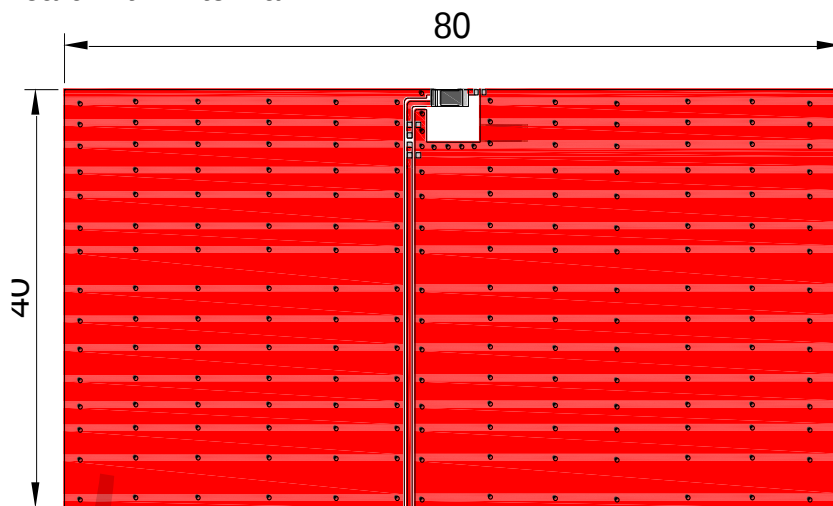
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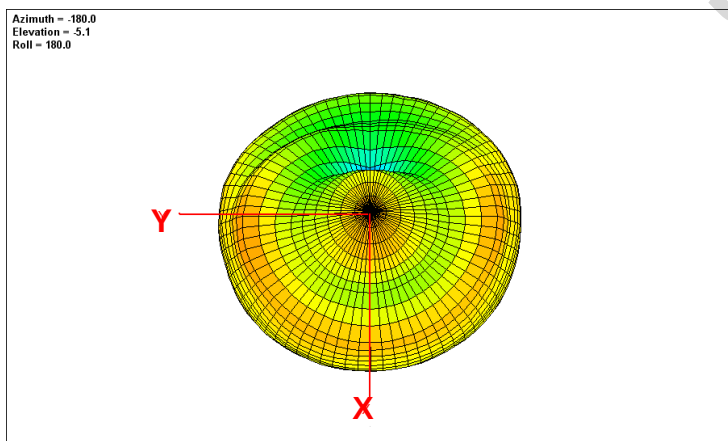
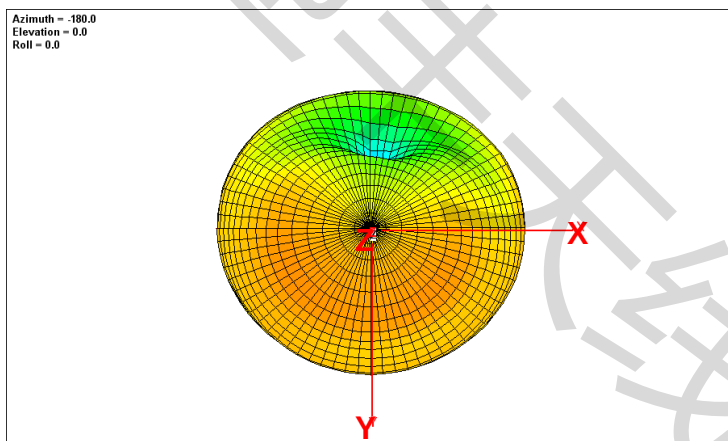
## b. Test Board with Antenna



Unit: mm

## 7. Radiation Pattern (80 x 40 mm<sup>2</sup> ground plane)

### 7-1. 3D Gain Pattern @ 2442 MHz



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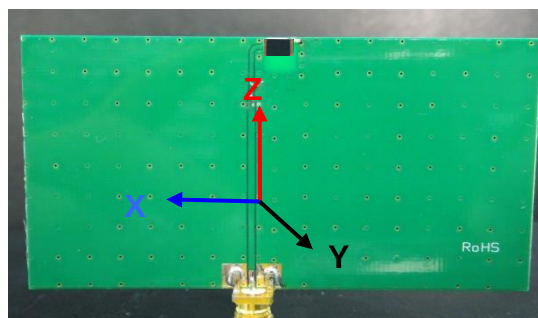
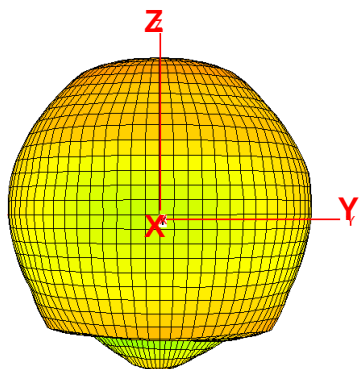
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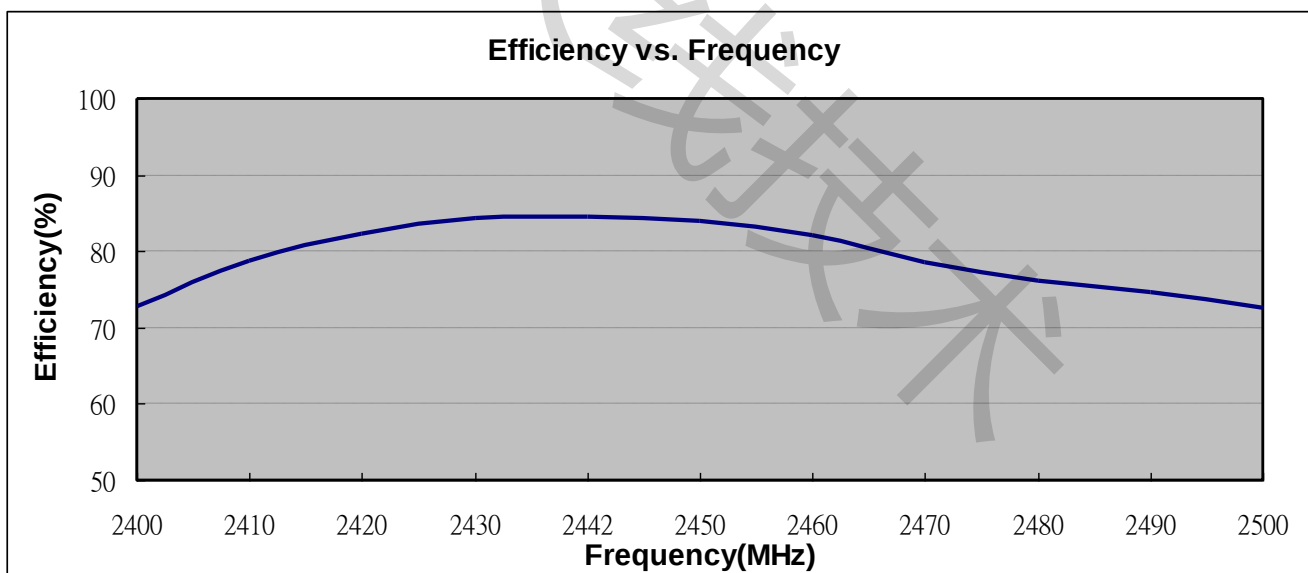
Azimuth = 0.0  
 Elevation = -90.0  
 Roll = 180.0



## 7-2. 3D Efficiency Table

| Frequency( MHz) | 2400 | 2410 | 2420 | 2430 | 2442 | 2450 | 2460 | 2470 | 2480 | 2490 | 2500 |
|-----------------|------|------|------|------|------|------|------|------|------|------|------|
| Efficiency (dB) | -1.4 | -1.0 | -0.9 | -0.7 | -0.7 | -0.8 | -0.9 | -1.1 | -1.2 | -1.3 | -1.4 |
| Efficiency (%)  | 72.8 | 73.7 | 74.3 | 74.4 | 75.5 | 75.0 | 74.0 | 73.6 | 73.1 | 72.6 | 71.5 |
| Gain (dBi)      | 2.1  | 2.2  | 2.3  | 2.4  | 2.5  | 2.5  | 2.4  | 1.8  | 1.7  | 1.6  | 1.4  |

## 7-3. 3D Efficiency vs. Frequency



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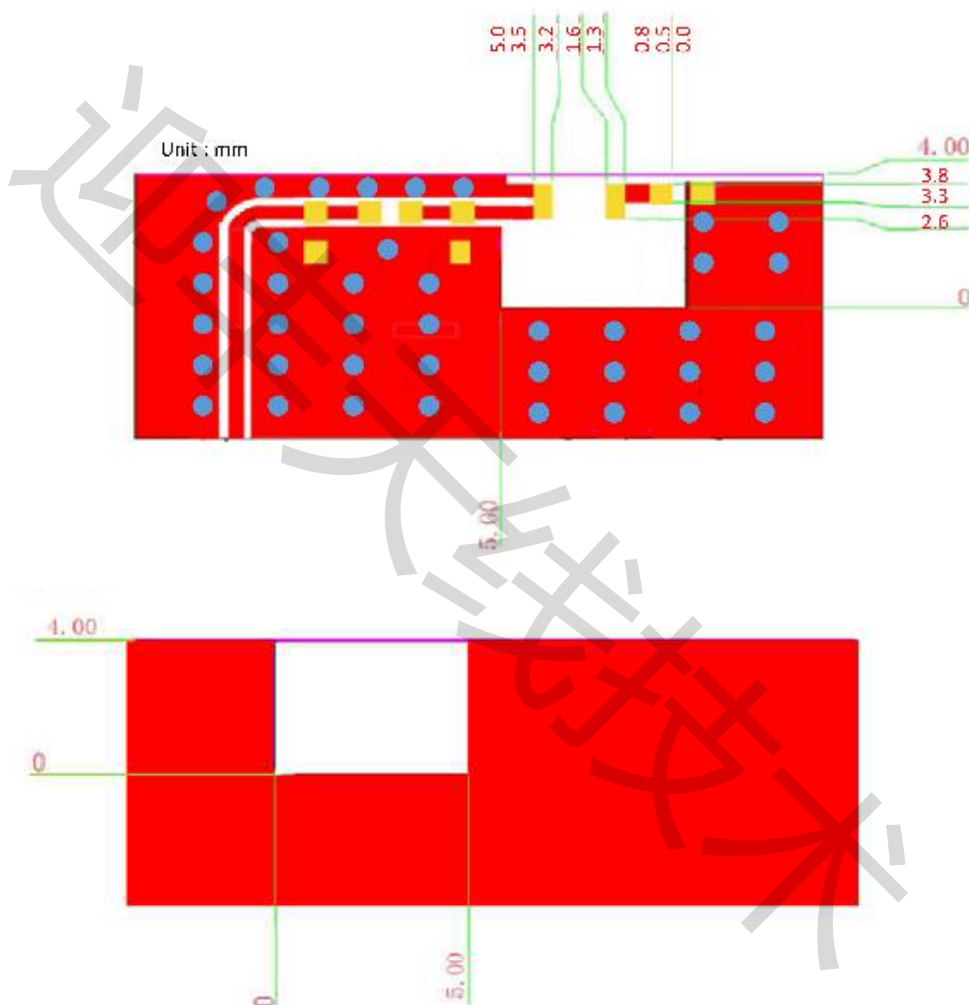
## 8. Layout Guide

### a. Solder Land Pattern:

Land pattern for soldering (gray marking areas) is as shown below. Depending on Customer's requirement, matching circuit as shown below is also recommended.

### 2). PCB Top View :

Type1 :



Bottom View



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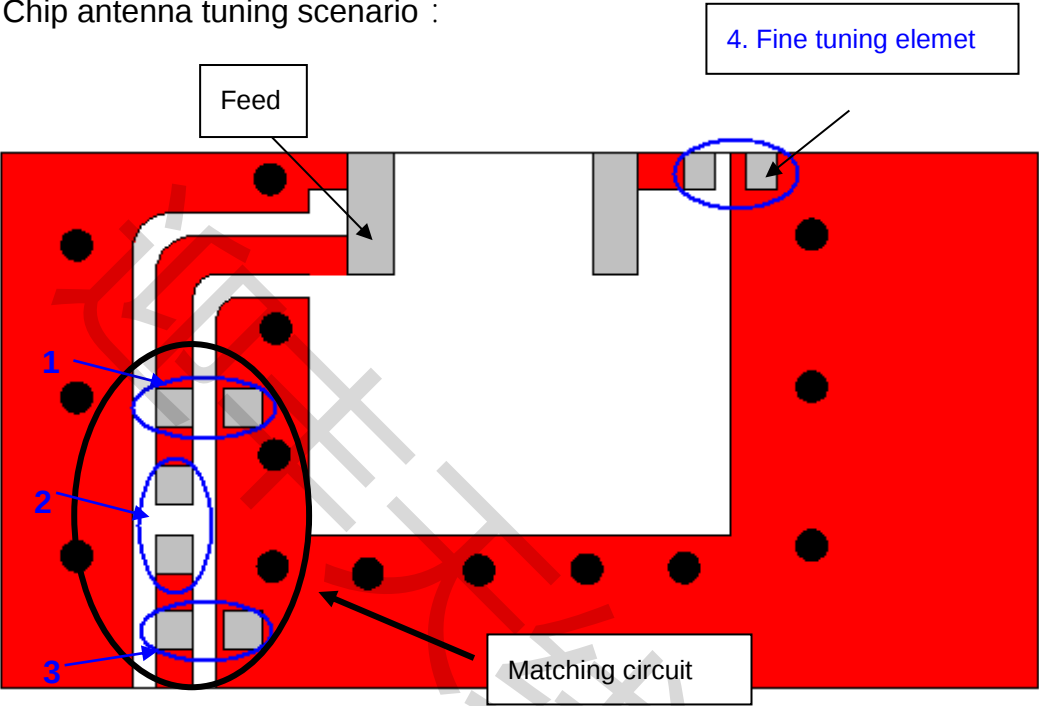
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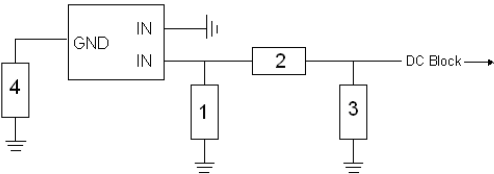
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9. Frequency tuning

a. Chip antenna tuning scenario :



b. Matching circuit : (Center frequency is about 2442 MHz @ 80 x 40 mm<sup>2</sup> ground plane)



| System Matching Circuit Component |             |               |               |
|-----------------------------------|-------------|---------------|---------------|
| Location                          | Description | Vendor        | Toleranc<br>e |
| 1                                 | 1.2 pF*     | Murata (0402) | ±0.1 pF       |
| 2                                 | 10PF*       | Murata(0402)  | ±0.5 PF       |
| 3                                 | N/A*        | -             | -             |
| Fine tuning<br>element<br>4       | 1.5 pF*     | Murata (0402) | ±0.1 pF       |

\*Typical reference values which may need to be changed when circuit



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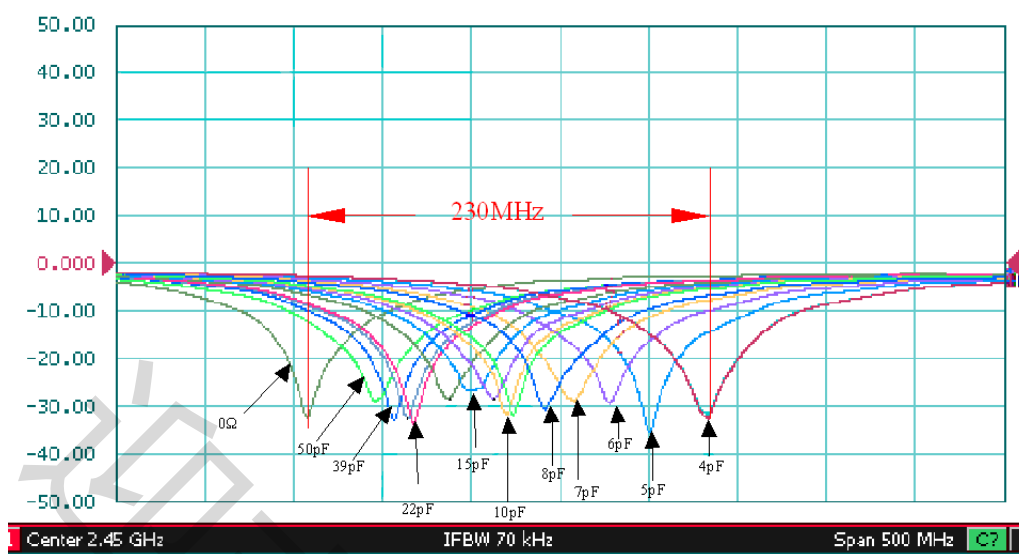
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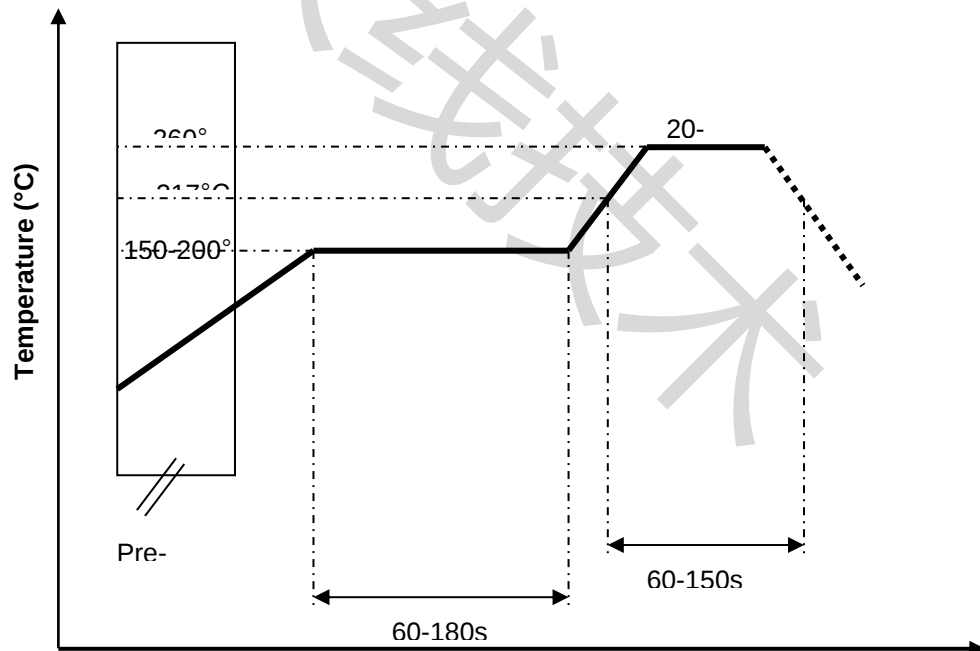
boards or part vendors are different.

c. Fine tuning element vs. Center frequency



## 10. Soldering Conditions

a. Typical Soldering Profile for Lead-free Process



Time  
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11. Packing

- (1) Quantity/Reel: 5000 pcs/Reel
- (2) Plastic tape:

Reel and Taping Specification

Reel Specification

The diagram shows a top view and a side view of a reel. The top view is a circle with a central hub and four spokes. Dimensions are labeled: A (radius from center to outer edge), B (outer diameter), C (inner diameter of the hub), D (hole diameter in the hub), M (width of the reel), and W (flange width). The side view shows the profile of the reel with dimensions W (flange width), D (hole diameter), and M (width).

| TYPE | SIZE | A       | φ B     | φ C      | φ D    | W      | φ M     |
|------|------|---------|---------|----------|--------|--------|---------|
| 2012 | 7"   | 5K/Reel | 2.0±0.5 | 13.5±1.0 | 21±1.0 | 60±1.0 | 178±2.0 |

Tapping Specification

The diagram shows a side view of a carrier tape. Dimensions are labeled: A (pitch between components), B (width of the tape), P (pitch between holes), D (hole diameter), E (width of the tape), F (width of the tape), G (width of the tape), H (width of the tape), T (height of the tape), and I (height of the tape). A 'Paper Carrier' is also indicated.

| Packaging  | Type | A         | B         | W        | E         | F        | G        | H        | T         | φD                  | P       |
|------------|------|-----------|-----------|----------|-----------|----------|----------|----------|-----------|---------------------|---------|
| Paper Type | 2012 | 1.90±0.20 | 3.50±0.20 | 8.0±0.20 | 1.75±0.10 | 3.5±0.05 | 4.0±0.10 | 2.0±0.05 | 0.75±0.10 | 1.50<br>+0.10<br>-0 | 4.0±0.1 |



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## Reliability Table

| Test Item                             | Procedure                                                                                                                                                                                                                                                                                         | Requirements<br>Ceramic Type                                                | Remark<br>(Reference)     |
|---------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------|---------------------------|
| Electrical<br>Characterization        |                                                                                                                                                                                                                                                                                                   | Fulfill the electrical<br>specification                                     | User Spec.                |
| Thermal<br>Shock                      | 1. Preconditioning:<br>50 ± 10°C / 1 hr, then keep for 24 ± 1 hrs at room temp.<br>2. Initial measure: Spec: refer Initial spec.<br>3. Rapid change of temperature test:<br>-30°C to +85°C; 100 cycles;<br>15 minutes at Lower category temperature;<br>15 minutes at Upper category temperature. | No Visible Damage.<br>Fulfill the electrical<br>specification.              | MIL-STD-202<br>107        |
| Temperature<br>Cycling                | 1. Initial measure: Spec: refer Initial spec.<br>2. 100 Cycles (-30°C to +85°C), Soak Mode=1 (2 Cycle/hours).<br>3. Measurement at 24 ± 2Hours after test condition.                                                                                                                              | No Visible Damage.<br>Fulfill the electrical<br>specification.              | JESD22<br>JA104           |
| High Temperature<br>Exposure          | 1. Initial measure: Spec: refer Initial spec.<br>2. Unpowered; 500hours @ T=+85°C.<br>3. Measurement at 24 ± 2 hours after test.                                                                                                                                                                  | No Visible Damage.<br>Fulfill the electrical<br>specification.              | MIL-STD-202<br>108        |
| Low Temperature<br>Storage            | 1. Initial measure: Spec: refer Initial spec.<br>2. Unpowered; 500hours @ T= -30°C.<br>3. Measurement at 24 ± 2 hours after test.                                                                                                                                                                 | No Visible Damage.<br>Fulfill the electrical<br>specification.              | MIL-STD-202<br>108        |
| Solderability<br>(SMD Bottom Side)    | Dipping method:<br>a. Temperature: 235 ± 5°C<br>b. Dipping time: 3 ± 0.5s                                                                                                                                                                                                                         | The solder should cover<br>over 95% of the critical<br>area of bottom side. | IEC 60384-21/22<br>4.10   |
| Soldering Heat<br>Resistance<br>(RSH) | Preheating temperature: 150 ± 10°C.<br>Preheating time: 1~2 min.<br>Solder temperature: 260 ± 5°C.<br>Dipping time: 5 ± 0.5s                                                                                                                                                                      | No Visible Damage.                                                          | IEC 60384-21/22<br>4.10   |
| Vibration                             | 5g's for 20 min., 12 cycles each of 3 orientations<br>Note: Use 8"x5" PCB .031" thick 7 secure points on, one long<br>side and 2 secure points at corners of opposite sides. Parts<br>mounted within 2" from any secure point. Test from 10-2000<br>Hz.                                           | No Visible Damage.                                                          | MIL-STD-202<br>Method 204 |
| Mechanical<br>Shock                   | Three shocks in each direction shall be applied along the three<br>mutually perpendicular axes of the test specimen (18 shocks)<br>Peak value: 1,500g's<br>Duration: 0.5ms<br>Velocity change: 15.4 ft/s<br>Waveform: Half-sine                                                                   | No Visible Damage.                                                          | MIL-STD-202<br>Method 213 |
| Humidity<br>Bias                      | 1. Humidity: 85% R.H., Temperature: 85 ± 2 °C.<br>2. Time: 500 ± 24 hours.<br>3. Measurement at 24 ± 2hrs after test condition.                                                                                                                                                                   | No Visible Damage.<br>Fulfill the electrical<br>specification.              | MIL-STD-202<br>Method 106 |



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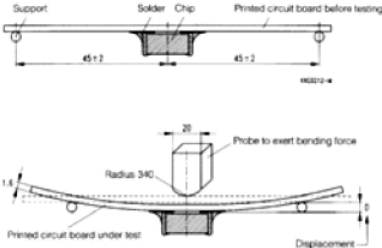
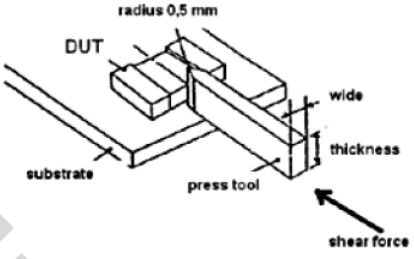
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| Board Flex (SMD)   | <p>1. Mounting method:<br/>IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm)</p> <p>2. Apply the load in direction of the arrow until bending reaches 2 mm.</p>  | No Visible Damage.                                                                                                                                                       | AEC-Q200 005 |
| Adhesion           | <p>Force of 1.8Kg for 60 seconds.</p>                                                                                                                       | No Visible Damage<br>Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction. | AEC-Q200 006 |
| Physical Dimension | Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.                                                       | In accordance with specification.                                                                                                                                        | JESD22 JB100 |



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